



2004 IEEE



Compound Semiconductor IC Symposium

(Formerly GaAs IC Symposium)



INTEGRATED CIRCUITS IN GaAs, InP, SiGe, GaN and OTHER COMPOUND SEMICONDUCTORS

October 24 – 27, 2004

Monterey, California, USA



Sponsored by the IEEE Electron Devices Society
Technically co-sponsored by the IEEE Solid State Circuits Society
and the IEEE Microwave Theory & Techniques Society



FIRST CALL FOR PAPERS

2004 IEEE Compound Semiconductor IC Symposium

Over the last 26 years, the IEEE GaAs IC Symposium has become the preeminent international forum on developments in integrated circuits using compound semiconductors such as GaAs, InP, GaN, SiGe and other materials. In this first year under our new name, the IEEE Compound Semiconductor IC Symposium, we continue in the same tradition. Coverage embraces all aspects of the technology, from materials issues and device fabrication, through IC design and testing, high volume manufacturing, and system applications. The IEEE Compound Semiconductor IC Symposium (CSICS) provides the ideal forum to present your latest results in high-speed digital, analog, microwave/millimeter wave, mixed mode, and optoelectronic integrated circuits. First-time papers concerned with the utilization and application of InP, GaAs, SiGe, GaN and other compound semiconductors in military and commercial products are invited. Specific technical areas of interest include:

- Innovative RFIC Device & Circuit Concepts
- Circuit Design & Fabrication
- Manufacturing Technology & Cost Issues
- CAD/CAM/CAT Tools & Techniques
- IC Testing & Methodology
- Packaging Technology
- Reliability
- Advanced Device Applications
- System Applications (e.g., wireless, vehicular, RADAR, military)
- Optoelectronic and OEIC applications

Symposium Highlights

Over 70 technical papers will be selected from worldwide submissions for oral presentation and publication in the Symposium Digest. Invited papers and panel sessions on topics of current importance to the Compound Semiconductor IC community will complete the program. Extended versions of selected papers from the Symposium will be published in a special issue of the *IEEE Journal of Solid State Circuits*.

Compound Semiconductor Primer Course

The Symposium will again offer the popular primer course, "Basics of GaAs, InP and SiGe RFICs," which is an introductory-level class intended for those wishing to obtain a broad overview of RFIC technology. The Sunday evening course will cover materials and processes, device operation, and both analog/microwave and digital ICs. The Course will be tailored to provide the specific background needed for participants to understand and appreciate the papers presented in the Symposium Technical Program.

Short Course

A short course will be held on Sunday, October 24th. The course is currently under development and will cover current topics in the industry. Organizer: Mitch Shifrin, Hittite Microwave Corp., e-mail: mitchs@hittite.com, phone: 1.978.250.3343.

Deadline for Electronic Receipt of Abstracts is

Close of Business, May 3, 2004

Authors must submit one-page abstracts of results not previously published or not already accepted by another conference. Additional supporting material (2 pages maximum) may also be submitted at the discretion of the authors. Papers will be selected on the basis of the abstract.

The abstract must concisely and clearly state:

- The purpose of the work
- What specific new results have been obtained
- How it advances the state-of-art or the industry
- References to prior state-of-art
- Sub-committee preference:
 - Digital OEIC,
 - Analog RF/Microwave,
 - or Technology/Manufacturing

The abstract and supporting material must include: the title, name(s) of the author(s), organization(s) represented, correspondence authors' postal and electronic addresses, and telephone and FAX numbers. Please indicate your preference for subcommittee review. The program committee will honor the authors' preference where possible, but reserves the right to place the paper in other review categories.

Company and governmental clearances must be obtained prior to submission of the abstract.

The accepted one-page abstracts may be used for publicity purposes. Portions of these abstracts may be quoted in magazine articles publicizing the Symposium. **Please note on the abstract if this is not acceptable.**

Letters of acceptance or rejection will be mailed to authors by June 20, 2004. Authors of accepted papers will be required to submit a 4-page camera-ready extended abstract by August 22, 2004 for publication in the Symposium Technical Digest.

Please e-mail a one page abstract with up to two pages of supporting material to:

2004abstract@sirenza.com

Submissions must be in *.doc or *.pdf format only.

Submissions must be electronic. No hard copies accepted.

Further questions on abstract submission may be addressed to the Symposium Technical Program Chair:

Kevin Kobayashi
TEL: 1-310-257-0569
Email: kkobayashi@sirenza.com

All Symposium information, including abstract submission instructions and a link to our abstract submission address is also available on our website at:

<http://www.csics.org/>

2004 Compound Semiconductor IC Symposium Exhibition

As in past years, the Symposium will sponsor an exhibition of products from various vendors of materials, IC products, processing equipment, test equipment, CAD tools, and foundry services specifically addressing the Compound Semiconductor industry. Numerous vendors will be on-hand to discuss their products and to answer questions.

Inquiries concerning the exhibits should be addressed to: Harry Kuemmerle, III, VIP Meetings and Conventions, 1515 Palisades Drive, Suite I, Pacific Palisades CA 90272-2113.

Phone: +1-310-459-4691 or

FAX: +1-310-459-0605, or

Email: vipmtgs@aol.com

The following members of the Technical Program Committee are available for guidance or for answering questions regarding abstract preparation:

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